WHAT IS CLAIMED IS:

1) An improved process for manufacture and assembly of a plurality of adjoined printed wiring boards, comprising:

(a) forming at least a first circuit pattern and a second circuit pattern on a common substrate;

(b) connecting at least the first circuit pattern to the second circuit pattern; and

(c) separating the common substrate into at least a first substrate and a second substrate with the first substrate including the first circuit pattern thereon and the second substrate including the second circuit pattern thereon.

2) The process of **claim 1**, further comprising the step of scoring the common substrate along a dividing line.

3) The process of **claim 1**, further comprising the step holding the separated substrates in fixed position relative to each other by a holding fixture.

4) The process of **claim 1**, further comprising the step of testing the connection between the first and second circuit patterns prior to the step of separating the common substrate into separate substrates.

5) The process of **claim 1**, wherein the step of separating occurs after the step of connecting.

6) The process of **claim 3**, wherein the step of connecting occurs after the step of separating.

7) The process of **claim 1**, wherein:

(a) the common substrate comprises at least a first substrate section and a second substrate section;

(b) the step of forming comprises forming a plurality of circuit patterns on the first substrate section and a plurality of circuit patterns on the second substrate section; and

(c) the step of connecting further comprises making a plurality of connections between circuit patterns on the first substrate section and the second substrate section.

8) The process of **claim 1**, wherein the step of separating further comprises pressing the common substrate along a dividing line until it separates into at least the first and second substrates.

9) The process of **claim 1**, wherein the step of separating further comprises cutting the common substrate into a plurality of separate substrates.

10) The process of **claim 1**, wherein the step of connecting further comprises attaching at least one electrically conductive wire.

11) The process of **claim 10**, wherein the at least one electrically conductive wire comprises a pre-insulated wire.

12) The process of **claim 1**, wherein the step of connecting further comprises attaching flexible ribbon wires.

13) The process of **claim 1**, wherein the step of connecting further comprises using at least one electrically conductive plastic connection.

14) The process of **claim 3**, wherein the step of holding further comprises using a holding fixture for holding at least one of the separated substrates at a non-planar angle in respect to another separated substrate.

15) The process of **claim 3**, wherein the step of holding further comprises holding at least one of the separated substrates in proximity to a frame member of an assembly that includes at least one of the separated substrates.

16) The process of **claim 15**, wherein one separated substrate is held in proximity to one frame member and at least another separated substrate is held in proximity to a second frame member.

17) The process of **claim 15**, wherein the frame member is a sidewall of a cabinet for housing the assembly that contains at least one of the separated substrates.

18) The process of **claim 2**, wherein the step of scoring comprises forming a groove in the common substrate, said groove having sides angled at less than 60 degrees.

19) The process of **claim 1**, wherein the step of separating further comprises using an edged tool placed in contact with the common substrate along a dividing line.

20) The process of **claim 3**, wherein the step of connecting further comprises making at least one connection that is external from the holding fixture.